6/4/08 10/796,427

CAS/STN

Patent Citation Index

FILE 'PCI' ENTERED AT 16:50:23 ON 04 JUN 2008
E JP09232898/PN

E JP09232898/PN.D
E JP9232898/PN.D

FILE 'HCAPLUS' ENTERED AT 16:50:52 ON 04 JUN 2008
E JP 9232898/RE

E JP 09232898/RE

Chemical Abstracts

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     CAS/STN FILE 'WPIX' ENTERED AT 08:18:36 ON 04 JUN 2008
L1             5 SEA ABB=ON  PLU=ON  (US6963138 OR US5886414 OR US6451681 OR
                 US6544880 OR US6383916)/PN
L2               SEL PLU=ON  L1 1- PN :       7 TERMS

     FILE 'PCI' ENTERED AT 08:18:40 ON 04 JUN 2008  (Patent Citation Index)
L3            51 SEA ABB=ON  PLU=ON  L2/PN.D
L4               SEL PLU=ON  L3 1- PRN :      54 TERMS

     FILE 'WPIX, JAPIO, HCAPLUS, KOREAPAT' ENTERED AT 08:19:51 ON 04 JUN 2008
L5           137 SEA ABB=ON  PLU=ON  L4
L6           120 SEA ABB=ON  PLU=ON  L5 AND US/PC
L7               SEL PLU=ON  L6 1- PRN :     160 TERMS
L8           269 SEA ABB=ON  PLU=ON  L7
L9             0 SEA ABB=ON  PLU=ON  L5 NOT L8
L10           19 SEA ABB=ON  PLU=ON  L5 AND KR/PC
L11              SEL PLU=ON  L10 1- PRN :      18 TERMS

     FILE 'STNGUIDE' ENTERED AT 08:27:05 ON 04 JUN 2008

     FILE 'HCAPLUS, KOREAPAT, INSPEC, COMPENDEX, METADEX, DISSABS' ENTERED AT
     08:28:19 ON 04 JUN 2008

     FILE 'HCAPLUS, KOREAPAT, INSPEC, COMPENDEX, METADEX, DISSABS, NTIS'
     ENTERED AT 08:28:26 ON 04 JUN 2008
L12         3601 SEA ABB=ON  PLU=ON  (WIREBOND#### OR BONDWIR###### OR WIR##(A)
BOND##### OR PAD OR BONDPAD OR (BOND#### OR PAD)(A) CONTACT)(6A)(WIRE OR LINE OR TRACE
OR LEAD OR RIBBON OR CONDUCTOR)(3A)(AU OR GOLD OR PRECIOUS OR NOBLE OR METAL#####)
L13          229 SEA ABB=ON  PLU=ON  (IMMEDIATE## OR DIRECT##) AND L12
L14           88 SEA ABB=ON  PLU=ON  L12 AND (CAP OR CAPP####)
L15          659 SEA ABB=ON  PLU=ON  L12 AND (BARRIER OR ADHE######)

     FILE 'STNGUIDE' ENTERED AT 08:29:57 ON 04 JUN 2008

     FILE 'REGISTRY' ENTERED AT 08:32:00 ON 04 JUN 2008
L16            1 SEA ABB=ON  PLU=ON  GOLD/CN
L17        14162 SEA ABB=ON  PLU=ON  GOLD ALLOY
L18         9268 SEA ABB=ON  PLU=ON  AU>50/MAC
L19          146 SEA ABB=ON  PLU=ON  TI.W/MF
L20         3911 SEA ABB=ON  PLU=ON  TITANIUM ALLOY AND W/ELS
L21         4611 SEA ABB=ON  PLU=ON  TUNGSTEN ALLOY AND TI/ELS
L22            1 SEA ABB=ON  PLU=ON  TITANIUM/CN
L23            1 SEA ABB=ON  PLU=ON  ALUMINUM/CN
L24       129819 SEA ABB=ON  PLU=ON  ALUMINUM ALLOY
L25        87364 SEA ABB=ON  PLU=ON  AL>50/MAC

     FILE 'STNGUIDE' ENTERED AT 08:32:06 ON 04 JUN 2008

     FILE 'HCAPLUS' ENTERED AT 08:38:02 ON 04 JUN 2008
L26         1081 SEA ABB=ON  PLU=ON  L12 AND (L16 OR L17 OR L18 OR AU OR GOLD)
L27          149 SEA ABB=ON  PLU=ON  L12 AND (L19 OR L20 OR L21 OR L22 OR TI OR
                 TIW OR WTI OR TITANIUM)
L28          507 SEA ABB=ON  PLU=ON  L12 AND (L23 OR L24 OR L25 OR AL OR
                 ALUMINIUM OR ALUMINUM)

     FILE 'STNGUIDE' ENTERED AT 08:38:59 ON 04 JUN 2008
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     FILE 'HCAPLUS' ENTERED AT 08:39:56 ON 04 JUN 2008
L29             0 SEA ABB=ON  PLU=ON  US20050017361
                  E US20050017361/PN
L30             1 SEA ABB=ON  PLU=ON  US20050017361/PN
L31               SEL PLU=ON  L30 1- IC IPC NCL ECLA FTERM :       16 TERMS

     FILE 'STNGUIDE' ENTERED AT 08:40:24 ON 04 JUN 2008

     FILE 'HCAPLUS' ENTERED AT 08:40:52 ON 04 JUN 2008
L32         44850 SEA ABB=ON  PLU=ON  L31
L33           399 SEA ABB=ON  PLU=ON  L12 AND L32
L34           173 SEA ABB=ON  PLU=ON  L33 NOT US/PC
L35           109 SEA ABB=ON  PLU=ON  L34 AND 1990-2003/PY,PRY
L36            23 SEA ABB=ON  PLU=ON  L34 AND 1970-1989/PY,PRY
L37           124 SEA ABB=ON  PLU=ON  L35 OR L36
L38           226 SEA ABB=ON  PLU=ON  L33 NOT L34
L39           173 SEA ABB=ON  PLU=ON  L38 AND 1985-2003/PY,PRY
L40           297 SEA ABB=ON  PLU=ON  L37 OR L39

     FILE 'STNGUIDE' ENTERED AT 08:42:41 ON 04 JUN 2008

     FILE 'HCAPLUS' ENTERED AT 08:43:21 ON 04 JUN 2008
L41            69 SEA ABB=ON  PLU=ON  L26 AND L27 AND L28
L42            27 SEA ABB=ON  PLU=ON  L41 AND L40
                  D BIB AB IT 1-27

     FILE 'STNGUIDE' ENTERED AT 08:43:54 ON 04 JUN 2008

     FILE 'HCAPLUS' ENTERED AT 08:46:16 ON 04 JUN 2008
L43           270 SEA ABB=ON  PLU=ON  L40 NOT L42
L44           117 SEA ABB=ON  PLU=ON  L43 NOT US/PC
L45            27 SEA ABB=ON  PLU=ON  L13 AND (L14 OR L15)
L46            15 SEA ABB=ON  PLU=ON  L14 AND L15
L47           200 SEA ABB=ON  PLU=ON  L12 AND JOIN#####
L48            59 SEA ABB=ON  PLU=ON  L47 AND (L13 OR L14 OR L15)
L49           340 SEA ABB=ON  PLU=ON  (L44 OR L45 OR L46 OR L47 OR L48)
L50           333 SEA ABB=ON  PLU=ON  L49 NOT L42
L51           279 SEA ABB=ON  PLU=ON  L50 NOT US/PC
L52           220 SEA ABB=ON  PLU=ON  L51 AND 1980-2003/PY,PRY
L53            12 SEA ABB=ON  PLU=ON  L51 AND 1970-1979/PY,PRY
L54           229 SEA ABB=ON  PLU=ON  L52 OR L53
L55           194 SEA ABB=ON  PLU=ON  L54 AND ?WIRE?
L56           197 SEA ABB=ON  PLU=ON  L54 AND ?BOND?

     FILE 'STNGUIDE' ENTERED AT 08:48:21 ON 04 JUN 2008

     FILE 'HCAPLUS' ENTERED AT 08:49:42 ON 04 JUN 2008
L57            68 SEA ABB=ON  PLU=ON  L54 AND (COMPRESS##### OR PRESSURE OR
                  TENSION OR TENSILE OR STRAIN##### OR STRESS###### OR FAIL#####
                  OR MECH OR MECHANICAL###)
L58            39 SEA ABB=ON  PLU=ON  L54 AND (DAMAG#### OR PROTECT##### OR
                  SHIELD##### OR PREVENT#####)
L59             0 SEA ABB=ON  PLU=ON  L54 AND ILD
L60             0 SEA ABB=ON  PLU=ON  L54 AND IMD
L61             1 SEA ABB=ON  PLU=ON  L54 AND INTER
L62            15 SEA ABB=ON  PLU=ON  L54 AND INTERMETAL?
L63             4 SEA ABB=ON  PLU=ON  L54 AND INTERPOS?
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L64            6 SEA ABB=ON  PLU=ON  L54 AND INTERL?
L65            0 SEA ABB=ON  PLU=ON  L54 AND SEED######
L66            2 SEA ABB=ON  PLU=ON  L54 AND NUCLE#####
L67            0 SEA ABB=ON  PLU=ON  L54 AND ISLAND
L68            0 SEA ABB=ON  PLU=ON  L54 AND DOT
L69           89 SEA ABB=ON  PLU=ON  L54 AND (WIRE? OR BONDWIR? OR WIREBOND?)/TI

L70            8 SEA ABB=ON  PLU=ON  L54 AND ?PASSIVAT?
L71            0 SEA ABB=ON  PLU=ON  L54 AND POSTPASSIVAT?
L72            0 SEA ABB=ON  PLU=ON  L54 AND POST PASSIVAT?
L73           42 SEA ABB=ON  PLU=ON  L54 AND INTERCONNECT?
L74           32 SEA ABB=ON  PLU=ON  L54 AND (CU OR COPPER)(7A)(AU OR GOLD OR
                 AL OR ALUMIN###### OR TI OR TIW OR WTI OR TITANIUM)
L75          166 SEA ABB=ON  PLU=ON  (L57 OR L58 OR L59 OR L60 OR L61 OR L62 OR
                 L63 OR L64 OR L65 OR L66 OR L67 OR L68 OR L69 OR L70 OR L71 OR
                 L72 OR L73 OR L74)
L76          139 SEA ABB=ON  PLU=ON  L75 AND L55 AND L56
L77           32 SEA ABB=ON  PLU=ON  L76 AND (AU OR GOLD)(6A)(AU OR GOLD)
L78           49 SEA ABB=ON  PLU=ON  L76 AND (AU OR GOLD)/TI
L79          114 SEA ABB=ON  PLU=ON  L76 AND (AU OR GOLD)
L80           37 SEA ABB=ON  PLU=ON  L76 AND (AU OR GOLD)(6A)(AL OR CAP OR
                 CAPP##### OR ALUMIN####### OR TI OR TIW OR TITANIUM)
L81            7 SEA ABB=ON  PLU=ON  L76 AND (AU OR GOLD)(6A)(BARRIER OR
                 ADHE######)
L82            2 SEA ABB=ON  PLU=ON  L76 AND (AL OR CAP OR CAPP##### OR
                 ALUMIN#######)(9A)(TI OR TIW OR TITANIUM)

     FILE 'STNGUIDE' ENTERED AT 08:55:45 ON 04 JUN 2008

     FILE 'HCAPLUS' ENTERED AT 08:56:38 ON 04 JUN 2008
L83            88 SEA ABB=ON  PLU=ON  (L61 OR L62 OR L63 OR L64 OR L65 OR L66 OR
                 L67 OR L68) OR L70 OR (L77 OR L78) OR (L80 OR L81 OR L82)

     FILE 'STNGUIDE' ENTERED AT 08:56:39 ON 04 JUN 2008

     FILE 'HCAPLUS' ENTERED AT 08:57:36 ON 04 JUN 2008
L84            42 SEA ABB=ON  PLU=ON  L83 AND (MECH OR MECHANIC###### OR
                 COMPRESS###### OR STRESS#### OR STRAIN##### OR TEST###### OR DUT)

     FILE 'STNGUIDE' ENTERED AT 08:58:08 ON 04 JUN 2008

     FILE 'HCAPLUS' ENTERED AT 09:00:46 ON 04 JUN 2008
L85            46 SEA ABB=ON  PLU=ON  (L83 NOT L84) AND L12
L86             7 SEA ABB=ON  PLU=ON  (L83 NOT L84) AND L13
L87             0 SEA ABB=ON  PLU=ON  (L83 NOT L84) AND L14
L88            14 SEA ABB=ON  PLU=ON  (L83 NOT L84) AND L15
L89            16 SEA ABB=ON  PLU=ON  (L86 OR L87 OR L88)
                 D BIB AB IT TOT

     FILE 'STNGUIDE' ENTERED AT 09:01:57 ON 04 JUN 2008

     FILE 'HCAPLUS, COMPENDEX, INSPEC, DISSABS, NTIS, METADEX, KOREAPAT'
     ENTERED AT 09:37:19 ON 04 JUN 2008
L90           473 SEA ABB=ON  PLU=ON  (AU OR GOLD)(2W)(?BOND? OR JOIN?)(2W)(AU
                 OR GOLD)

     FILE 'STNGUIDE' ENTERED AT 09:37:45 ON 04 JUN 2008
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FILE 'HCAPLUS, COMPENDEX, INSPEC, DISSABS, NTIS, METADEX, KOREAPAT'
ENTERED AT 09:38:06 ON 04 JUN 2008

L91 79 SEA ABB=ON PLU=ON (AU OR GOLD)(2W)(DIRECT## OR IMMEDIATE##)(2W)(AU OR GOLD)

FILE 'STNGUIDE' ENTERED AT 09:38:12 ON 04 JUN 2008

FILE 'HCAPLUS, COMPENDEX, INSPEC, DISSABS, NTIS, METADEX, KOREAPAT'
ENTERED AT 09:39:25 ON 04 JUN 2008

L92 16 SEA ABB=ON PLU=ON (IMMEDIATE## OR DIRECT##)(4A)(JOIN##### OR BOND#### OR ATTACH####)(4A)(AU OR GOLD)(4W)(AU OR GOLD)

FILE 'STNGUIDE' ENTERED AT 09:39:34 ON 04 JUN 2008

FILE 'HCAPLUS, COMPENDEX, INSPEC, DISSABS, NTIS, METADEX, KOREAPAT'
ENTERED AT 09:40:02 ON 04 JUN 2008

L93 2304 SEA ABB=ON PLU=ON (IMMEDIATE## OR DIRECT## OR JOIN##### OR BOND#### OR ATTACH####)(4A)(AU OR GOLD)(4W)(AU OR GOLD)

FILE 'STNGUIDE' ENTERED AT 09:40:11 ON 04 JUN 2008

FILE 'HCAPLUS, COMPENDEX, INSPEC, DISSABS, NTIS, METADEX, KOREAPAT'
ENTERED AT 09:41:35 ON 04 JUN 2008

L94 379 SEA ABB=ON PLU=ON (L90 OR L91 OR L92 OR L93) AND (WIREBOND### ## OR BONDWIR##### OR WIR###(2A)(BOND#### OR PAD OR CONTACT) OR BONDPAD#### OR PADBOND#### OR PAD(3A) ?BOND?)
L95 77 SEA ABB=ON PLU=ON L94 AND AU/TI
L96 158 SEA ABB=ON PLU=ON L94 AND GOLD/TI
L97 161 SEA ABB=ON PLU=ON L94 AND GOLD/AB
L98 191 SEA ABB=ON PLU=ON L94 AND AU/AB
L99 347 SEA ABB=ON PLU=ON (L95 OR L96 OR L97 OR L98)
L100 140 SEA ABB=ON PLU=ON L99 AND (GOLD(5W) GOLD)
L101 180 SEA ABB=ON PLU=ON L99 AND (AU(5W) AU)
L102 63 SEA ABB=ON PLU=ON L99 AND (GOLD(5A) AU)
L103 302 SEA ABB=ON PLU=ON (L100 OR L101 OR L102)
L104 6 SEA ABB=ON PLU=ON L103 AND (SEED##### OR NUCLE###### OR ISLAND)
L105 214 SEA ABB=ON PLU=ON L103 AND (AU OR GOLD)(2A)(WIRE OR BONDWIRE)
L106 128 SEA ABB=ON PLU=ON L103 AND (AU OR GOLD)(2A)(LAYER OR PAD OR CONTACT)
L107 70 SEA ABB=ON PLU=ON L103 AND (AU OR GOLD)(2A)(FILM OR COAT##### OR MEMBRAN#####)
L108 115 SEA ABB=ON PLU=ON L105 AND (L106 OR L107)
L109 115 SEA ABB=ON PLU=ON L108 AND WIRE
L110 113 SEA ABB=ON PLU=ON L108 AND BOND#####
L111 4 DUP REM L104 (2 DUPLICATES REMOVED)
L112 113 SEA ABB=ON PLU=ON L108 NOT L104
L113 101 DUP REM L112 (12 DUPLICATES REMOVED)
L114 44 SEA ABB=ON PLU=ON L113 AND 1995-2003/PY
L115 14 SEA ABB=ON PLU=ON L113 AND 1985-1994/PY
L116 17 SEA ABB=ON PLU=ON L113 AND 1970-1984/PY
L117 74 SEA ABB=ON PLU=ON (L114 OR L115 OR L116)
L118 10 SEA ABB=ON PLU=ON L117 AND JOIN#####
L119 3 SEA ABB=ON PLU=ON L117 AND (DIRECT## OR IMMEDIATE##)
L120 13 SEA ABB=ON PLU=ON (L118 OR L119)

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	252	"6963138" or "5886414" or "6451681" or "6544880" or "6383916"	US-PGPUB; USPAT	OR	OFF	2008/06/04 10:28
L2	84	L1 and (au or gold) near4 (ball$7 or 9bond$7 or wirebond$6 or wir$5 or pad or contact or seed$6 or island or dot)	US-PGPUB; USPAT	OR	OFF	2008/06/04 10:39
L7	7	L2 and ("1995" or "1996" or "1997" or "1998" or "1999" or "2000" or "2001" or "2002" or "2003").py.	US-PGPUB; USPAT	OR	OFF	2008/06/04 10:39
L8	5	L2 and ("1995" or "1996" or "1997" or "1998" or "1999" or "2000" or "2001" or "2002" or "2003").pry.	US-PGPUB; USPAT	OR	OFF	2008/06/04 10:39
L9	5	L8 not L7	US-PGPUB; USPAT	OR	OFF	2008/06/04 10:40

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	"7306823"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 13:04
L2	2	"20040170753"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:02
L3	1	"20050017361"	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:07
L4	112473	L04-C12$ or L04-C13B$ or L04-F03$ or U11-C05D3$ or U11-C05D4$ or U11-D03B2$	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:10
L5	20701	H01L23/485$ or H01L23/522$ or H01L23/532$	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:10
L6	3120	H01L023/485$ or H01L023/522$ or H01L023/532$	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:08
L7	501	wirebond$	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:08
L8	26038	wire adj bond$4	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:08
L9	38	bondwir$5	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:08
L10	4342	bond adj wir$5	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:09
L11	154152	L4 or L5 or L6 or L7 or L8 or L9 or L10	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:13
L12	1930	(bondwir$7 or wirebond$7 or wiring or wire) near4 (join$5 or fasten$6 or connect$6 or weld$6 or adher$4 or immediate$2 or direct$2 or against or adjacent or proximity or locat$6 or position$6 or nearby or interconnect$6 or soldered or soldering) near4 (au or gold)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:43

EAST Search History

L13	498	L11 and L12	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:17
L14	38	(bondwir$7 or wirebond$7 or wiring or wire) near4 (contacting or contacted) near4 (au or gold)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:19
L15	1616	(bondwir$7 or wirebond$7 or wiring or wire) near4 (layer$7 or coat$6 or cap$7 or film$2) near4 (au or gold)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:19
L16	0	L13 and L14	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:19
L17	86	L13 and L15	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:19
L18	6	L14 and L15	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:19
L19	22	(L17 or L18) and au	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:20
L20	80	(L17 or L18) and gold	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:20
L21	2	(L17 or L18) and (precious or noble) adj metal	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:20
L22	92	L19 or L20 or L21	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:20
L23	44	L22 and (gold or au or precious or noble) near4 (wirebond$6 or bondwir$6 or (bond$4 adj wir$4) or (wir$4 adj bond$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:23
L24	11	L23 and (L4 or L5 or L6)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:29
L25	276	(au or gold) near3 (film$2 or layer$5 or interpos$6 or inter or interlayer$6 or overlayer$6 or multilayer$6 or bilayer$6 or trilayer$6 or coat$6) near6 (bondwir$6 or wirebond$6 or (wir$5 adj bond$5) or (bond$5 adj wir$5))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:32
L26	22	L25 and L23	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:32

EAST Search History

L27	16	L26 not L24	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:33
L28	11228	(al or aluminium or aluminum) near3 (cap or capp$4 or top or lid or lidd$5 or toplayer$5 or overlayer$6 or overcoat$6 or topcoat$5 or atop or over or above)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:34
L29	98710	(al or aluminium or aluminum) near3 (layer$7 or film$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:35
L30	29950	(al or aluminium or aluminum) near3 coat$6	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:35
L31	0	L27 and L28	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:35
L32	2	L27 and L29	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:35
L33	1	L27 and L30	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:36
L34	2	L32 or L33	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:37
L35	28	L23 not (L27 or L34)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:37
L36	7	L35 and (au or gold) near4 (grain or island or seed$6 or nucle$8 or isola$8 or dot or dots or cryst$8 or polycryst$7 or position$6 or loci or locus or locat$7 or monocryst$8 or amorph$6 or noncryst$7 or metal$7)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:40
L37	3100	(bondwir$7 or wirebond$7 or wiring or wire) near7 (join$5 or fasten$6 or connect$6 or weld$6 or adher$4 or immediate$2 or direct$2 or against or adjacent or proximity or locat$6 or position$6 or nearby or interconnect$6 or soldered or soldering) near7 (au or gold or noble or precious)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:44
L38	23	L27 or L34 or L36	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:44

EAST Search History

L39	3078	L37 not L38	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:45
L40	1000	L39 and us	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:45
L41	328	L39 and us.pc.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:45
L42	2750	L39 not L41	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:45
L43	1429	L42 and ("2003" or "2002" or "2001" or "2000" or "1999" or "1998" or "1997" or "1996" or "1995" or "1994" or "1993" or "1992" or "1991" or "1990").py.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:46
L44	615	L42 and ("1989" or "1988" or "1987" or "1986" or "1985" or "1984").py.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:47
L45	2034	L43 or L44	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:47
L46	2300	L42 not ("2008" or "2007" or "2006" or "2005" or "2004").py.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:48
L47	2359	L45 or L46	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:48
L48	29	L47 and (electrodep$7 or electroplat$6 or plated or deposited) near4 (gold or au) adj layer$5	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:52
L49	9	L47 and (electrodep$7 or electroplat$6 or plated or deposited) near4 (gold or au) adj film	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:52
L50	10	L47 and (electrodep$7 or electroplat$6 or plated or deposited) near1 (gold or au) adj film	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:53
L51	178	L47 and (electrodep$7 or electroplat$6 or plate$5 or deposit$5) near1 (gold or au)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:53
L52	181	L48 or L49 or L50 or L51	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:53

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L53	15	L47 and (al or aluminum or aluminium) near2 (cap$5 or lid$7 or over$8 or top$7 or top or above or atom or upper$6)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:55
L54	1	L52 and L53	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:56
L55	194	(L52 or L53) not L54	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:56
L56	0	L55 and goldplat$5	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:57
L57	8	L55 and (au or gold) near2 (electro or electroplat$6 or electrodep$9)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:00
L58	186	L55 not L57	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 14:57
L59	61	L58 and (protect$7 or prevent$8 or isolat$7 or barrier$7 or damag$7 or test$7)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:01
L60	12	L59 and (cap$7 or al or aluminium or aluminum) near12 (au or gold)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:06
L62	49	L59 not L60	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:07
L63	4	L62 and (al or aluminum or aluminium) near8 (cap$6 or adhe$7 or barrier)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:09
L64	45	L62 not L63	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:11
L65	0	L64 and (L04-C12$ or L04-C13B$ or L04-F03$ or U11-C05D3$ or U11-C05D4$ or U11-D03B2$)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:10
L66	0	L64 and (H01L23/485$ or H01L23/522$ or H01L23/532$)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:12
L67	0	L64 and (H01L023/485$ or H01L023/522$ or H01L023/532$)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:11
L68	0	L64 and H01L23/485$ and (H01L23/522$ or H01L23/532$)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:12

EAST Search History

L69	0	L64 and (H01L23/522$ and H01L23/532$)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:12
L70	0	L64 and (H01L023/522$ and H01L023/532$)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:13
L71	0	L64 and H01L023/485$ and (H01L023/522$ or H01L023/532$)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/03 15:21
L74	2	"6963138" or "5886414"	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:49
L75	18147	(protect$5 or prevent$7) near8 (damag$6 or fail$6 or active or mechanic$7 or stress$6 or strain$6 or compress$7 or tension$6 or twist$6 or torqu$7 or fatig$7 or break$7) near5 (bond$7 or wir$8 or gold oaau or pad or interconnect$6)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:40
L76	375	(active) near8 (damag$6 or fail$6 or mechanic$7 or stress$6 or strain$6 or compress$7 or tension$6 or twist$6 or torqu$7 or fatig$7 or break$7) near5 (bond$7 or wir$8 or gold oaau or pad or interconnect$6)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:40
L77	1298	L11 and L75	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:40
L78	52	L11 and L76	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:40
L79	1331	L77 or L78	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:40
L80	9	L79 and (au or gold or ausn or aucu or aual or auag or aupt or aupd or snau or cuau or agau alau or agau or ptau or pdau) adj (film or layer)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:43
L81	17	L79 and (au or gold or ausn or aucu or aual or auag or aupt or aupd or snau or cuau or agau alau or agau or ptau or pdau) near2 (film or layer)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:43
L82	0	L79 and (au or gold or ausn or aucu or aual or auag or aupt or aupd or snau or cuau or agau alau or agau or ptau or pdau) near2 (seed$7 or nucle$8)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:43

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L83	17	L80 or L81	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:43
L84	8	L83 not (us.pc.)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:47
L85	2	"06120356"	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:47
L86	1	L85 not L84	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:48
L87	37749	(stress$6 or compress$6 or strain$6 or pressur$7 or fail$7 or damag$7) near4 mechanical$6	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:50
L88	335296	(stress$6 or compress$6 or strain$6 or pressur$7 or fail$7 or damag$7) near4 (protect$7 or prevent$7 or buffer$7)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:51
L89	18181	(mechanic$7) near4 (protect$7 or prevent$7 or buffer$7)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:51
L90	349549	L88 or L89	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:51
L91	368	L90 and ((gold or au).ti. or (gold or au) near2 (film or layer))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:52
L92	39	L91 and L11	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:52
L93	14	L92 and (cap$8 or al or aluminum or aluminium)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:53
L94	6	L93 not us.pc.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:55
L95	25	L92 not L93	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 15:55
L96	13	L95 not us.pc.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 16:02
L97	2	"06120356"	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/03 16:02

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1. Gold wire bonding at room temperature
Chen, Kim H. / Chan, Chun Yee / Choi, Soojin / Nigos, Johnny Monis (Agilent Technologies, Inc. (a Delaware corporation)), *EUROPEAN PATENT APPLICATION*, Dec 2002
patno:EP1266715
...305 against the **gold bond pad** 307, with a force...vibrating the **gold wire** (201, 203) at...bond between the **gold wire** and **gold bond**...apparatus for bonding **gold wire** to a **gold bond**...for holding a **gold bonding wire** (303); a vibration...
Full text available at patent office. For more in-depth searching go to LexisNexis
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2. Room temperature gold wire bonding
Chen, Kim H. / Choi, Soojin / Chan, Chun Yee / Nigos, Johnny Monis, *UNITED STATES PATENT AND TRADEMARK OFFICE PRE-GRANT PUBLICATION*, Jan 2003
patno:US20030006271
...the **gold wire** and **gold bond pad**. 2. The method of...claim 1, wherein the **gold bond pad** has been plated...apparatus for bonding **gold wire** to a **gold bond pad**, comprising: a holder for holding a **gold bonding wire**; a vibration source...
Full text available at patent office. For more in-depth searching go to LexisNexis
similar results

3. Room temperature gold wire bonding
Chen, Kim H. / Choi, Soojin / Chan, Chun Yee / Nigos, Johnny Monis, *UNITED STATES PATENT AND TRADEMARK OFFICE PRE-GRANT PUBLICATION*, Jan 2003
patno:US20030006267
...the **gold wire** and **gold bond pad**. 2. The method of...claim 1, wherein the **gold bond pad** has been plated...apparatus for bonding **gold wire** to a **gold bond pad**, comprising: a holder for holding a **gold bonding wire**; a vibration source...
Full text available at patent office. For more in-depth searching go to LexisNexis
similar results

4. GOLD WIRE BONDING METHOD, DEVICE AND SYSTEM
CHEN, KIM H / CHOI, SOOJIN / CHAN CHUN YEE / NIGOS JOHNNY MONIS (AGILENT TECHNOL INC), *PATENT ABSTRACTS OF JAPAN*, Jan 2003
patno:JP2003031606
...method, a device and a system for **gold wire** bonding by which a **gold wire** is bonded at a lower temperature...bonding the **gold wire** 303 to a **gold bonding pad** 307 is provided with a holder...pressing the holder 301 against the **gold bonding pad** 307.
Full text available at patent office. For more in-depth searching go to LexisNexis
similar results

5. Hermetically sealed semiconductor device
Cain, Earl S. (Tribotech), *UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT*, Jun 1997
patno:US5635766
...of the oxide layers 32a, 32b. The **gold bond pad** may also comprise two thin layers...aluminum bonding pad and die. The **gold bond pad** 33 extends over the edges of the...bonding pad area is sealed by the **gold bonding pad** layer, which overlaps the protective...barrier layer is formed over the **gold bond pad** layer 33 to prevent the ingress of...
Full text available at patent office. For more in-depth searching go to LexisNexis
similar results

6. Hermetically sealed semiconductor device
Cain, Earl S. (Tribotech), *UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT*, Sep 1996
patno:US5557148
...of the oxide layers 32a, 32b. The **gold bond pad** may also comprise two thin layers...aluminum bonding pad and die. The **gold bond pad** 33 extends over the edges of the...bonding pad area is sealed by the **gold bonding pad** layer, which overlaps the protective...barrier layer is formed over the **gold bond pad** layer 33 to prevent the ingress of...
Full text available at patent office. For more in-depth searching go to LexisNexis
similar results

7. SAW FILTER CHIP AND ITS MANUFACTURE
NOGUCHI, KAZUSHIGE (OKI ELECTRIC IND CO LTD), *PATENT ABSTRACTS OF JAPAN*, Sep 1997

Google "gold pad" "gold bonding wire" Search Advanced Search Preferences

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nepp.nasa.gov/wirebond/Literatures/NA-GSFC-2004-01.pdf - Similar pages

A Preliminary Electron Backscatter Diffraction Study of ...
gold bump and the **gold pad**. 11. When the ultrasonic. power is low, the ultrasonic energy applied is .... J. Seuntjens, **Gold Bonding Wire** Alloys 26 (2002). ...
www.springerlink.com/index/D3583T137Q5302P3.pdf - Similar pages

The Wirebonded Interconnect: A Mainstay for Electronics
a uniform gold welded interface, if both gold wire and **gold pad** or ..... There is great interest in replacing **gold bonding wire** with copper wire both for ...
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Incrementally etched electrical feedthroughs for wafer-level ...
gold pad acting as etch-stop layer (Figure Ih). Then, the glass lids are cut out by dicing their ... pm thick **gold bonding wire** to ...
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Studies on the high-temperature superconductor (HTS)/metal/polymer ...
ion was used to clean the bottom of the via (the **gold pad**. on HTS) and also to enhance the metal ..... materials development such as **gold bonding wire**, ...
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1) a third **gold pad** for the thermal contact is. added in the centre of the film. In this latter case, ... by the **gold bonding wire**. The detectors work in ...
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A **gold pad** was also exposed to allow for a ball-bonded. electrical connection between the UME array and a pad on the ... The **gold bonding wire** was then ...
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second design a third **gold pad** in the center of the. Im is used for the thermal contact. ..... and can be adjusted by the **gold bonding wire**. Our ...
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A Preliminary EBSD Study ofMicrostructures and Microtextures ...
demonstrated the characterization of **gold bonding wires** .... solid diffusion between the gold bump and the **gold pad**. [11]. When the ultrasonic ...
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A Preliminary Electron Backscatter Diffraction Study of ...
of **gold bonding wires** at various stages of process-. ing, from casting through wire drawing. .... gold bump and the **gold pad**. 11. When the ultrasonic ...
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1) a third **gold pad** for the thermal contact is. added in the centre of the film. ... is the thermal conductance of the **gold bonding wires**. ...
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[PS] Performance of the CRESST detectors and status of the experiment ...
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second design a third **gold pad** in the center of the. Im is used for the thermal contact. ... conductance of the **gold bonding wires**. Detector ...
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Electrical resistance of metallic contacts on silicon and ...
gold bonding wires used to make electrical contact to the. I ^ p : " : •••'•• .... i.e., the thickness of the **gold pad**, thereby demonstrating ...
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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3328	postpassivat$6 or ((post or prior or before or subsequen$8 or sequen$7 or "steps" or after or method or process$6 or first or next or then) near2 passivat$8)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 08:15
L2	19150	(two or three or sublayer$6 or sub or lamina$8 or multi$8 or stack$7 or sandwich$7 or triple or double or bilayer$6 or di or interpos$7 or interl$7 or interpos$7 or under$8 or below or above or multilayer$6 or start$7 or seed$7 or nucleat$8 or island$4 or deposit$6 or depd or depn or film or mambrane or coat$5 or subcoat$5 or topcoat$6 or overcoat$5 or toplayer$5 or over$7 or cluster$7 or dot or nanodot or microdot or sam or monolayer$6 or selfassemb$7 or self adj assembl$6) near2 (au or gold or au$2 or agau or snau or cuau or alau)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/05 08:22
L3	31790	(electrodep$8 or electro or electroless$5 or electrolytic$5 or electroplat$6 or plat$5 or pad or bondpad or padbond$6 or contact or electrode or cap or capp$4 or rectang$5 or sheet or foil or square or shap$6) near2 (au or gold or au$2 or agau or snau or cuau or alau)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/05 08:24
L4	2687	(bondwir$6 or wirebond$5 or wire or wiring) near5 (immediate$2 or direct$2 or bonded or bonding or against or connecting or touch$6) near5 (au or gold or au$2 or agau or snau or cuau or alau)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/05 08:26
L5	46010	L2 or L3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/05 08:26
L9	11	L1 and L4	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:15
L10	75	L1 and L5	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:15
L11	818	L4 and L5	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:16

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L12	4	L9 and L10 and L11	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:16
L13	896	L9 or L10 or L11	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:17
L14	896	L13 and (au or gold or au$2 or agau or snau or cuau or alau)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:19
L15	4	L13 and A679	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:19
L16	896	L14 or L15	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:19
L17	6	L16 and wirebond$6	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:19
L18	0	L16 and bondwir$7	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:20
L19	832	L16 and (bond$6 or connect$6 or interconnect$6 or contact$6 or pad$6 or electrode) near6 wir$5	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:21
L20	402	L16 and (au or gold) near3 (electro or electroless$3 or electroplat$6 or plat$6 or seed$6 or nucle$7 or cluster$7 or staret$7 or initia$7)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:22
L21	10	L15 or L17	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:22
L22	10	L21 not L12	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:23
L23	397	L20 not L22	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:23
L24	10	L22	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:29
L25	35	L23 and (adhe$7 or gluing or glue$3 or buffer$7 or promot$7 or barrier or block$7 or antidiffus$7 or antimigrat$7 or electrodiffus$7 or electromigra$7 or ti or titanium or tiw or wti) and (cap or capp$6 or al or aluminum or aluminium)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:31

EAST Search History

L26	21	L25 not us.pc.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:52
L27	2	"62048047"	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:53
L28	82	L1 and (L9 or L10 or L11)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:53
L29	9	seed$7 and (L9 or L10 or L11)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:53
L30	1	nucleat$6 and (L9 or L10 or L11)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:53
L31	12	island$7 and (L9 or L10 or L11)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:54
L32	2	cluster$7 and (L9 or L10 or L11)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:54
L33	33	(sub or under$7 or first or initia$7 or start$6) near2 (au$2 or gold or snau or cuau or alau or agau or pdau or ptau) and (L9 or L10 or L11)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:55
L34	16	L12 or L22 or L27	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:56
L35	125	L28 or L29 or L30 or L31 or L32 or L33	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:56
L36	97	L35 not (L34 or L25)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:57
L37	59	L36 not us.pc.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:57
L38	29	L37 and ("2003" or "2002" or "2001" or "2000" or "1998" or "1997" or "1996" or "1995" or "1994" or "1993" or "1992" or "1991" or "1990").py,pry.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:58
L39	6	L37 and ("2008" or "2007" or "2006" or "2005" or "2004").py.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:59

EAST Search History

L40	53	L37 not L39	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:59
L41	55	L38 or L40	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 09:59
L42	31	L41 and (seed$6 or nucleat$7 or cluster$7 or sam or selfassemb$7 or assembl$7 or monolayer$7 or (mono adj layer$7) or anchor$7 or sublayer$7 or (sub adj layer$6) or initia$7 or start$7 or goldplat$7 or plat$7 or electroplat$7)	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 10:02
L43	14	L41 and (au or gold or wirebond$7 or bondwir$7 or bond$5 or wir$5).ti.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 10:02
L44	34	L42 or L43	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/05 10:03
L45	1	1979-72409B.NRAN.	DERWENT	OR	OFF	2008/06/05 10:25